

IN THE SPECIFICATION

Please amend the paragraph bridging from p. 41 to p. 42 to read as follows:

In general, the greater the surface roughness, the greater will be the adhesion to dielectric material. However, as in the case of pre-treated CIC foil, too much roughness creates problems with etch resist patterning and stripping. In one embodiment, the process for creating micro-roughness includes use of BondFilm®, supplied by Atotech. This solution consists of 250 ml/l BondFilm® Part A and 35 ml/l BondFilm® Part B. The metal is immersed in this solution for 60 seconds at 35°C. In one embodiment, from about 0.5 to about 2 microns of metal is removed in the micro-roughening step of the present invention. Typically, the amount of copper removed by this process is from about 1.0 to about 1.5 microns, and the surface roughness (r_a), as measured by a profilometer, is for example, from about 0.2 to about 0.4 microns. By comparison, pre-treated CIC foil has surface roughness (r_a), as measured by a profilometer, in the range from about 1 to about 3 microns. The resist lock-in issues common to pre-treated foils are not likely to occur with micro-roughening processes using BondFilm® due to the lower surface roughness as compared to the pre-treated, e.g., dendritic surface.